

### **General Description**

The SJD024N06 uses SGT technology to provide excellent R<sub>DS(ON)</sub>, low gate charge and fast switching characteristics. This device is suitable for use as a wide variety of applications.

#### Features

- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

### Application

- DC/DC Converter
- Load Switching
- Power Management

## Key Performance Parametes

Parameter	Value	Unit
V <sub>DS</sub>	60	V
R <sub>DS(ON)_TYP</sub>	3	mΩ
ID	127	А
Q <sub>G</sub>	62	nC



Schematic Diagram

TO-252(DPAK) top view

### **Package Marking and Ordering Information**

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJD024N06	SJD024N06	TO-252	Таре	١	/	2500 Pcs

### Table 1. Absolute Maximum Ratings (T<sub>c</sub>=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V <sub>DS</sub>	Drain-Source Voltage (V <sub>GS</sub> =0V)	60	V
V <sub>GS</sub>	Gate-Source Voltage (V <sub>DS</sub> =0V)	±20	V
	Drain Current-Continuous(Tc=25℃)	127	А
Ι <sub>D</sub>	Drain Current-Continuous(Tc=100℃)	81	A
IDM (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	508	А
6	Maximum Power Dissipation(Tc=25°C)	106	W
PD	Maximum Power Dissipation(Tc=100°C)	42	W
Eas	Avalanche energy (Note 2)	552	mJ
TJ, TSTG	Operating Junction and Storage Temperature Range	-55 To 150	C

## Table 2. Thermal Characteristic

5	Symbol	Parameter	Тур	Max	Unit
	$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.18	°C/W



# SJD024N06

# **60V N-Channel SGT Power MOSFET**

## Table 3. Electrical Characteristics (T<sub>J</sub>=25 $^{\circ}$ C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States	-					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	60			V
		V <sub>DS</sub> =60V, V <sub>GS</sub> =0V TJ=25℃			1	μA
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V T <sub>J</sub> =125℃			100	μA
Igss	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA	1.1		2.1	V
gfs	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =20A		51		S
RDS(ON)	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A T <sub>J</sub> =25℃		3	3.8	mΩ
RDS(ON)	Drain-Source On-State Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A T <sub>J</sub> =25℃		3.7	4.9	mΩ
Dynamic Chara	cteristics					
Ciss	Input Capacitance			3680		pF
Coss	Output Capacitance	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V, f=1.0MHz		1230		pF
Crss	Reverse Transfer Capacitance			56		pF
Rg	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1.0MHz		0.74		Ω
Switching Para	meters	•				
t <sub>d(on)</sub>	Turn-on Delay Time			10		nS
tr	Turn-on Rise Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =30V, R <sub>L</sub> =1.5Ω, R <sub>GEN</sub> =6Ω		28		nS
t <sub>d(off)</sub>	Turn-Off Delay Time			54		nS
t <sub>f</sub>	Turn-Off Fall Time			30		nS
Qg	Total Gate Charge			62		nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =30V, I <sub>D</sub> =20A		10		nC
$Q_gd$	Gate-Drain Charge			14		nC
Source-Drain D	viode Characteristics					
I <sub>SD</sub>	Source-Drain Current (Body Diode)				127	Α
Vsd	Forward on Voltage (Note 3)	V <sub>GS</sub> =0V, I <sub>S</sub> =20A			1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I⊧=20A, dI/dt=100A/μs		57		ns
Qrr	Reverse Recovery Charge	I⊧=20A, dI/dt=100A/μs		70		nC

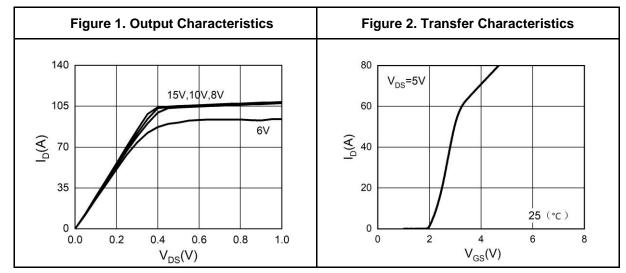
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

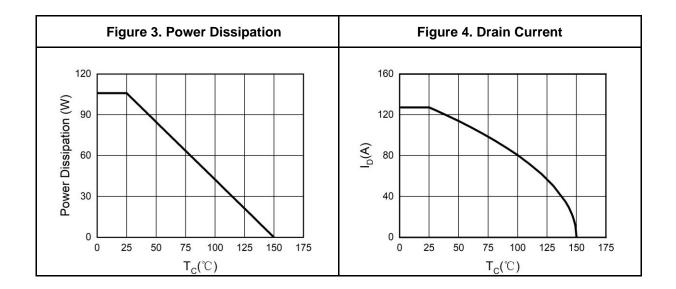
Notes 2.E<sub>AS</sub> condition:  $T_J=25^{\circ}C$ ,  $V_{DD}=40V$ ,  $V_G=10V$ ,  $Rg=25\Omega$ , L=0.5mH.

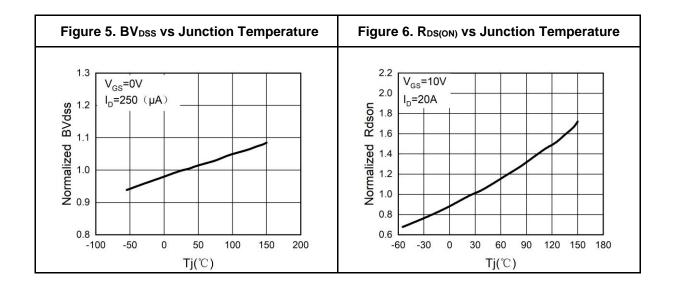
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## **Typical Electrical And Thermal Characteristics (Curves)**



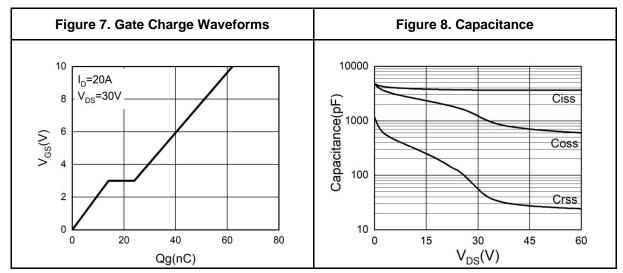


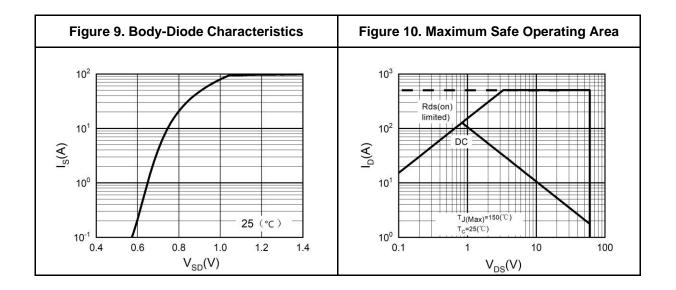




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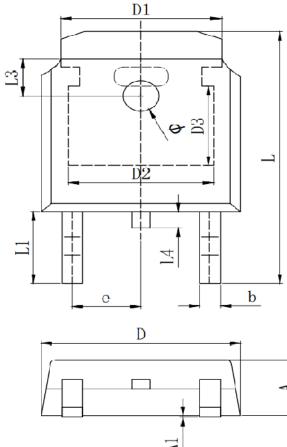
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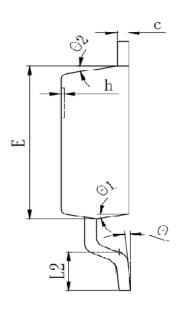






# **TO-252 Package Information**





Symbol	Dimensions In Millimeters				
Symbol	Min.	Тур.	Max.		
А	2.200	2.300	2.400		
A1	0.000		0.127		
b	0.640	0.690	0.740		
c(电镀后)	0.460	0.520	0.580		
D	6.500	6.600	6.700		
D1	5.334 REF				
D2	4.826 REF				
D3	3.166 REF				
E	6.000	6.100	6.200		
е		2.286 TYP			
h	0.000	0.100	0.200		
L	9.900	10.100	10.300		
L1		2.888 REF			
L2	1.400	1.550	1.700		
L3		1.600 REF			
L4	0.600	0.800	1.000		
Φ	1.100	1.200	1.300		
θ	0°		8°		
θ1		9° TYP			
θ2		9° TYP			



## Attention

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor

The performances and characteristics of this product in the independent testing state are displayed in this document. Wuxi Shangjia Semiconductor can't guarantee of the performances and characteristics of this described product that mounted in the customer's products or equipments as same as that in the independent testing state. So the customer should evaluate and test devices mounted in the customer's products or equipments.

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